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Products / NAND Flash / 3D NAND / 3D NAND Flash Part Catalog / MT29F512G08EBHBFJ4-T

MT29F512G08EBHBFJ4-T

Contact Sales

MT29F512G08EBHBFJ4-T:B			
Specs		Data Sheets	~
Chipset Validation	N/A	RoHS	~
Density	512Gb	Simulation Models	~
FBGA Code	NW966		
Op. Temp.	0C to +70C	Technical Notes	~
Part Status	Production	Customer Service Notes	~
Product Longevity Program	No		
Product Longevity Program Start Date	N/A		
Width	x8		

Products Solutions Support Insight About









